2.5-V PHASE LOCK LOOP CLOCK DRIVER WITH 2-LINE SERIAL INTERFACE

DGG PACKAGE

(TOP VIEW)

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lacktriangle	Phase-Lock Loop Clock Driver for Double
	Data-Rate Synchronous DRAM
	Applications
_	Spread Speatrum Clock Compatible

- Spread Spectrum Clock Compatible
- Operating Frequency: 60 to 140 MHz
- Low Jitter (cyc-cyc): ±75 ps
- Distributes One Differential Clock Input to Ten Differential Outputs
- Two-Line Serial Interface Provides Output Enable and Functional Control
- Outputs Are Put Into a High-Impedance State When the Input Differential Clocks Are <20 MHz
- 48-Pin TSSOP Package
- Consumes <250-μA Quiescent Current
- External Feedback Pins (FBIN, FBIN) Are Used to Synchronize the Outputs to the Input Clocks

description

The CDCV850 is a high-performance, low-skew, low-jitter zero delay buffer that distributes a differential clock input pair (CLK, $\overline{\text{CLK}}$) to ten differential pairs of clock outputs (Y[0:9], $\overline{\text{Y}[0:9]}$) and one differential pair of feedback clock outputs (FBOUT, $\overline{\text{FBOUT}}$). The clock outputs are con-

GND 48 **GND** <u>Y0</u> 47 T Y5 Y0 ∏ 46 N Y5 3 45 V_{DDQ} V_{DDQ} [] Y1 **∏** 44 Y6 <u>₹1</u> Ґ 43 Y6 6 **GND** 42 GND GND **1**8 41 GND 40 T Y7 9 39 Y7 Y2 **∏** 10 V_{DDQ} **∏** 11 SCLK II 12 37 N SDATA 36 FBIN CLK [13 CLK | 14 35 FBIN 15 $V_{DDI} \Pi$ 33 T FBOUT AV_{DD} AGND 17 32 | FBOUT GND | 18 31 GND 30 Y8 **Y3** 19 20 29 Y8 Y3 28 🕇 V_{DDQ} 21 V_{DDQ} Y4 Π 22 27 Y9 **∀**4 **1** 23 26 79 25 GND GND [

trolled by the clock inputs (CLK, $\overline{\text{CLK}}$), the feedback clocks (FBIN, $\overline{\text{FBIN}}$), the 2-line serial interface (SDATA, SCLK), and the analog power input (AV_{DD}). A two-line serial interface can put the individual output clock pairs in a high-impedance state. When the AV_{DD} terminal is tied to GND, the PLL is turned off and bypassed for test purposes.

The device provides a standard mode (100 Kbits/s) 2-line serial interface for device control. The implementation is as a slave/receiver. The device address is specified in the 2-line serial device address table. Both of the 2-line serial inputs (SDATA and SCLK) provide integrated pullup resistors (typically 100 k Ω).

Two 8-bit, 2-line serial registers provide individual enable control for each output pair. All outputs default to enabled at powerup. Each output pair can be placed in a high-impedance mode, when a low-level control bit is written to the control register. The registers must be accessed in sequential order (i.e., random access of the registers not supported). The serial interface circuit can be supplied with either 2.5 V or 3.3 V (at VDDI) in applications where this programming option is not required (after power up, all output pairs will then be enabled).

When the input frequency falls below a suggested detection frequency that is below 20 MHz (typically 10 MHz), the output pairs are put into a high-impedance condition, the PLL is shut down, and the device will enter a low power mode. The CDCV850 is also able to track spread spectrum clocking for reduced EMI.

Since the CDCV850 is based on PLL circuitry, it requires a stabilization time to achieve phase-lock of the PLL. This stabilization time is required following power up, as well as changes to various 2-line serial registers that affect the PLL. The CDCV850 is characterized in a temperature range from –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



AVAILABLE OPTIONS

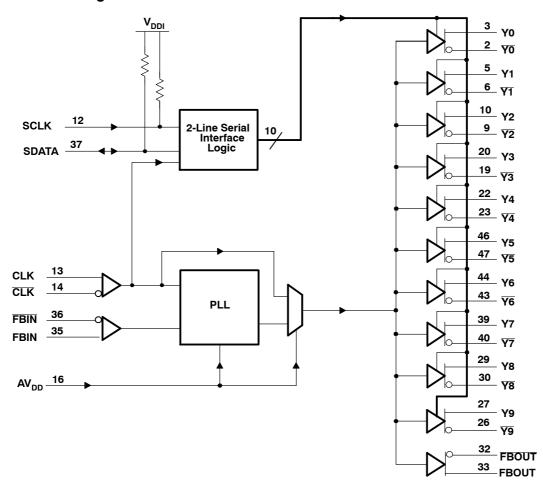
-	PACKAGED DEVICES				
I'A	TSSOP (DGG)				
−40°C to 85°C	CDCV850DGG				

FUNCTION TABLE (Select Functions)

	INPUTS			5. .				
AV _{DD}	CLK	CLK	Y[0:9]	Y[0:9]	FBOUT	FBOUT	PLL	
GND	L	Н	L	Н	L	Н	Bypassed/Off	
GND	Н	L	Н	L	Н	L	Bypassed/Off	
2.5 V (nom)	L	Н	L	Н	L	Н	On	
2.5 V (nom)	Н	L	Н	L	Н	L	On	
2.5 V (nom)	<20 MHz	<20 MHz	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Off	

[†] Each output pair (except FBOUT, FBOUT) can be put into a high-impedance state through the 2-line serial interface.

functional block diagram





Terminal Functions

TERMINAL NAME NO.							
		I/O	DESCRIPTION				
AGND	17		Ground for 2.5-V analog supply				
AV_{DD}	16		2.5-V analog supply				
CLK, CLK	13, 14	I	Differential clock input				
FBIN, FBIN	35, 36	ı	Feedback differential clock input				
FBOUT, FBOUT	32, 33	0	Feedback differential clock output				
GND	1, 7, 8, 18, 24, 25, 31, 41, 42, 48		Ground				
SCLK	12	I	Clock input for 2-line serial interface				
SDATA	37	I/O	Data input/output for 2-line serial interface				
V_{DDQ}	4, 11, 21, 28, 34, 38, 45		2.5-V supply				
V_{DDI}	15	ı	2.5-V or 3.3-V supply for 2-line serial interface				
		0	Buffered output copies of input clock, CLK				
Y[0:9]	2, 6, 9, 19, 23, 26, 30, 40, 43, 47	0	Buffered output copies of input clock, CLK				

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absolute maximum ratings over operating free-air temperature (unless otherwise noted)

Supply voltage range:	V _{DDQ} , AV _{DD}	0.5 V to 3.6 V
	V _{DDI}	0.5 V to 4.6 V
Input voltage range:	V _I (except SCLK and SDATA) (see Notes 1 and 2)	
	V _I (SCLK, SDATA) (see Notes 1 and 2)	0.5 V to V _{DDI} + 0.5 V
Output voltage range:	V _O (except SDATA) (see Notes 1 and 2)	–0.5 V to V _{DDQ} + 0.5 V
	V _O (SDATA) (see Notes 1 and 2)	–0.5 V to V _{DDQ} + 0.5 V
Input clamp current, II	$_{K}$ (V_{I} < 0 or V_{I} > V_{DDQ})	±50 mA
Output clamp current,	I_{OK} ($V_O < 0$ or $V_O > V_{DDQ}$)	±50 mA
Continuous output cur	rent, I_O ($V_O = 0$ to V_{DDQ})	±50 mA
Package thermal impe	edance, θ_{JA} (see Note 3): DGG package	89°C/W
Storage temperature	ange T _{stg}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This value is limited to 3.6 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			MIN	TYP	MAX	UNIT	
I Supply voltage		, AV _{DD}	2.3		2.7	.,	
Supply voltage	V_{DDI}	(see Note 5)	2.3		3.6	V	
	CLK,	CLK, HCSL Buffer only		0	0.24		
Low level input voltage, V _{IL}		CLK	-0.3		V _{DDQ} – 0.4		
		, FBIN			V _{DDQ} /2 – 0.18	V	
		ΓA, SCLK			$0.3 \times V_{DDI}$		
High level input voltage, V_{IH}		CLK, HCSL Buffer only	0.66	0.71			
		CLK	0.4		V _{DDQ} + 0.3		
		, FBIN	V _{DDQ} /2 + 0.18			V	
		ΓA, SCLK	$0.7 \times V_{DDI}$				
DC input signal voltage (see Note 6)	-0.3		V _{DDQ} + 0.3	V			
		CLK, FBIN	0.36		V _{DDQ} + 0.6	.,	
Differential input signal voltage, V _{ID} (see Note 7)	AC	CLK, FBIN	0.2		V _{DDQ} + 0.6	V	
Input differential pair cross-voltage, V_{IX} (see Note 8	3)		0.45×(V _{IH} -V _{IL})		$0.55 \times (V_{IH} - V_{IL})$	V	
High-level output current, I _{OH}					-12	mA	
In the state to the small t					12	V	
Low-level output current, I _{OL}		ГА			3	mA	
Input slew rate, SR (see Figure 8)	1		4	V/ns			
SSC modulation frequency	30		33.3	kHz			
SSC clock input frequency deviation	0		-0.50	kHz			
Operating free-air temperature, T _A			-40		85	°C	

- NOTES: 4. Unused inputs must be held high or low to prevent them from floating.
 - 5. All devices on the serial interface bus, with input levels related to V_{DDI}, must have one common supply line to which the pullup resistor is connected to.
 - 6. DC input signal voltage specifies the allowable dc execution of differential input.
 - 7. Differential input signal voltage specifies the differential voltage |VTR VCP| required for switching, where VTR is the true input level and VCP is the complementary input level.
 - 8. Differential cross-point voltage is expected to track variations of VCC and is the voltage at which the differential signals must be crossing.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		TEST	CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{IK}	Input voltage	All inputs	V _{DDQ} = 2.3 V,	I _I = -18 mA			-1.2	V
, , , , , , , , , , , , , , , , , , ,	High lavel and and		V_{DDQ} = min to m	ax, I _{OH} = -1 mA	V _{DDQ} - 0.1			.,
V _{OH}	High-level output	voitage	$V_{DDQ} = 2.3 V$,	$I_{OH} = -12 \text{ mA}$	1.7			V
			V_{DDQ} = min to m	ax, I _{OL} = 1 mA			0.1	
V_{OL}	Low-level output voltage		$V_{DDQ} = 2.3 V$,	I _{OL} = 12 mA			0.6	V
	voltage	SDATA	$V_{DDI} = 3.0 V$,	$I_{OL} = 3 \text{ mA}$			0.4	
I _{OH}	High-level output	current	$V_{DDQ} = 2.3 V$,	V _O = 1 V	-18	-32		mA
I_{OL}	Low-level output	current	$V_{DDQ} = 2.3 V$,	V _O = 1.2 V	26	35		mA
Vo	Output voltage sv	ving	For load conditio	n see Figure 3	1.1		$V_{DDQ} - 0.4$	>
V _{OX}	Output differentia voltage	l cross			V _{DDQ} /2 – 0.2	V _{DDQ} /2	V _{DDQ} /2 + 0.2	٧
l _i	Input current	SDATA, SCLK	V _{DDQ} = 3.6 V,	V _I = 0 V to 3.6 V			+10/–50	μА
	•	CLK, FBIN	$V_{DDQ} = 2.7 V$	V _I = 0 V to 2.7 V			±10	μΑ
l _{OZ}	High-impedance- current	state output	V _{DDQ} = 2.7 V,	$V_O = V_{DDQ}$ or GND			±10	μΑ
I _{DDPD}	Power-down curr + AV _{DD}	ent on V _{DDQ}	CLK at 0 MHz; Σ	of I _{DD} and AI _{DD}		150	250	μΑ
55.5	Power down curr	ent on V _{DDI}	CLK at 0 MHz; V	_{DDQ} = 3.6 V		3	20	μΑ
I _{DD}	Dynamic current on V _{DDQ}		V_{DDQ} = 2.7 V, f_{O} = 100 MHz All differential output pairs are terminated with 120 Ω / C_{L} = 4 pF			205	230	mA
AI _(DD)	Supply current or	ı AV _{DD}	$AV_{DD} = 2.7 \text{ V},$	f _O = 100 MHz		4	6	mA
I _{DDI}	Supply current on V _{DDI}		V _{DDI} = 3.6 V	SCLK and SDATA = 3.6 V		1	2	mA
C _I	Input capacitance)	V _{DDQ} = 2.5 V	V _I = V _{DDQ} or GND	2	2.5	3	pF
Co	Output capacitan	се	V _{DDQ} = 2.5 V	$V_O = V_{DDQ}$ or GND	2.5	3	3.5	pF

[†] All typical values are at respective nominal V_{DDQ} . ‡ The value of V_{OC} is expected to be |VTR + VCP|/2. In case of each clock directly terminated by a 120-Ω resistor, where VTR is the true input signal voltage and VCP is the complementary input signal voltage (see Figure 3).

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timing requirements over recommended ranges of supply voltage and operating free-air temperature

		MIN	MAX	UNIT
f _(CLK)	Clock frequency	60	140	MHz
	Input clock duty cycle	40%	60%	
	Stabilization time [†]		10	μs

[†] Time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal. For phase lock to be obtained, a fixed-frequency, fixed-phase reference signal must be present at CLK. Until phase lock is obtained, the specifications for propagation delay, skew, and jitter parameters given in the switching characteristics table are not applicable. This parameter does not apply for input modulation under SSC application.

timing requirements for the 2-line serial interface over recommended ranges of operating free-air temperature and VDDI from 3.3 V to 3.6 V (see Figure 10)

•		MIN	MAX	UNIT
f _(SCLK)	SCLK frequency		100	kHz
t _(BUS)	Bus free time	4.7		μs
t _{su(START)}	START setup time [†]	4.7		μs
t _{h(START)}	START hold time [†]	4.0		μs
t _{w(SCLL)}	SCLK low pulse duration	4.7		μs
t _{w(SCLH)}	SLCK high pulse duration	4.0		μs
t _{r(SDATA)}	SDATA input rise time		1000	ns
t _{f(SDATA)}	SDATA input fall time		300	ns
t _{su(SDATA)}	SDATA setup time	250		ns
t _{h(SDATA)}	SDATA hold time	0		ns
t _{su(STOP)}	STOP setup time	4		μs

[†] This conforms to I2C specification, version 2.1.



switching characteristics over recommended ranges of operating free-air temperature (unless otherwisw noted)

	PARAMETER		TEST CONDITIONS	MIN	TYP MAX	UNIT	
t _{pd}	Propagation delay time		Test mode/CLK to any output		4	ns	
t _{PHL}	High-to low-level propagation delay	SCLK to SDATA (acknowledge)		500 [†]	ns		
t _{en}	Output enable time	Test mode/SDATA to Y-output		85	ns		
t _{dis}	Output disable time	Test mode/SDATA to Y-output		35	ns		
t _{jit(per)}	Jitter (period), See Figure 6		100/133 MHz	-30	30	ps	
t _{jit(cc)}	Jitter (cycle-to-cycle), See Figure 3		100/133 MHz	-30	30	ps	
t _{jit(hper)}	Half-period jitter, See Figure 7		100/133 MHz	-75	75	ps	
			100 MHz/VID on CLK = 0.71 V [‡]	-120	120		
			100 MHz/VID on CLK = 0.59 V [§]	-50	160		
	Static phase offset, See Figure 4a	0°C to 85°C	100 MHz/VID on CLK = 0.82 V¶	-170	70	ps	
			133 MHz/VID on CLK = 0.71 V¶	-50	180		
$t_{(\varnothing)}$		-40°C to 85°C	100 MHz/VID on CLK = 0.71 V [‡]	-160	80		
			100 MHz/VID on CLK = 0.59 V [§]	-90	120		
			100 MHz/VID on CLK = 0.82 V¶	-210	30	ps	
			133 MHz/VID on CLK = 0.71 V [¶]	-80	150		
	Dynamic phase offset, SSC on, Sec	100 MHz/VID on CLK = 0.71 V [‡]	-190	190	ps		
#	Figure 9	133 MHz/VID on CLK = 0.71 V [‡]	-140	140	ps		
td _(∅) #	- · · · · · · · · · · · · · · ·		100 MHz/VID on CLK = 0.71 V [‡]	-160	160	ps	
	Dynamic phase offset, SSC off, Sec	133 MHz/VID on CLK = 0.71 V [‡]	-130	130	ps		
t _{slr(o)}	Output clock slew rate, terminated 120 Ω /14 pF, See Figures 1 and 8		1	2	V/ns		
t _{slr(o)}	Output clock slew rate, terminated with 120 Ω /4 pF, See Figures 1 and 8			1	3	V/ns	
t _{sk(o)}	Output skew, See Figure 5				75	ps	
. ,	SSC modulation frequency			30	33.3	kHz	
	SSC clock input frequency deviatio	n		0.00	-0.50	%	

 $^{^{\}dagger}$ This time is for a PLL frequency of 100 MHz.

 $^{^{\}ddagger}$ According CK00 spec: 6 x I $_{ref}$ at 50 Ω and R $_{ref}$ = 475 Ω

 $^{^\}S$ According CK00 spec: 5 x I $_{ref}$ at 50 Ω and R_{ref} = 475 Ω ¶ According CK00 spec: 7 x I $_{ref}$ at 50 Ω and R_{ref} = 475 Ω

[#] The parameter is assured by design but cannot be 100% production tested.

 $[\]parallel$ All differential output pins are terminated with 120 $\Omega/4$ pF

CDCV850 2.5-V PHASE LOCK LOOP CLOCK DRIVER WITH 2-LINE SERIAL INTERFACE

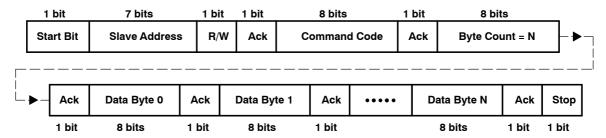
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2-line serial interface

2-line serial interface slave address

A 7	A6	A 5	A4	А3	A2	A 1	R/W
1	1	0	1	0	0	1	0

Writing to the device is accomplished by sequentially sending the device address $D2_H$, the dummy bytes (command code and the number of bytes), and the data bytes. This sequence is illustrated in the following tables:



2-line serial interface configuration command bitmap

The 2-line serial command bytes are used to control the output clock pairs (Y[0:9], Y[0:9]). The output clock pairs are enabled after power up. During normal operation, the clock pairs can be disabled (set Hi-Z) or enabled (running) by writing the corresponding bit to the data bytes in the following tables:

Byte 0: Enable/Disable Register (H = Enable, L = Disable)

Byte 1: Enable/Disable Register (H = Enable, L = Disable)

BIT	PINS	INITIAL VALUE	DESCRIPTION	BIT	PINS	INITIAL VALUE	DESCRIPTION
7	3, 2	Н	Y0, Y 0	7	29, 30	Н	Y8, Y 8
6	5, 6	Н	Y1, Y 1	6	27, 26	Н	Y9, Y 9
5	10, 9	Н	Y2, Y 2	5	_	L	Reserved
4	20, 19	Н	Y3, \overline{Y3}	4	-	L	Reserved
3	22, 23	Н	Y4, Y 4	3	-	L	Reserved
2	46, 47	Н	Y5, Y 5	2	-	L	Reserved
1	44, 43	Н	Y6, Y 6	1	-	L	Reserved
0	39, 40	Н	Y7, Y7	0	-	L	Reserved

PARAMETER MEASUREMENT INFORMATION

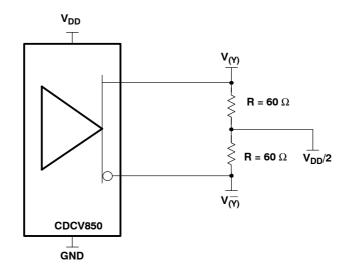


Figure 1. IBIS Model Output Load (used for slew rate measurement)

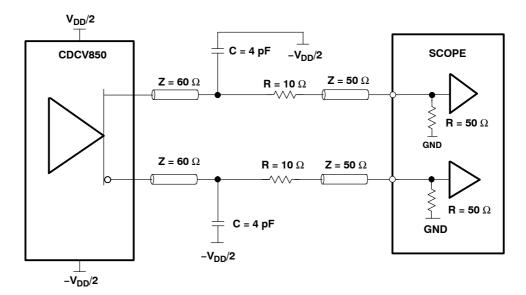


Figure 2. Output Load Test Circuit

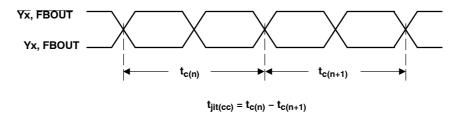
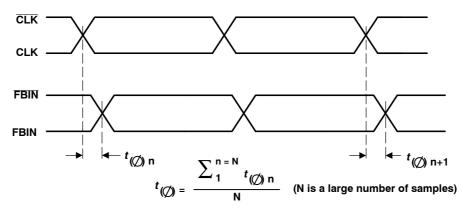


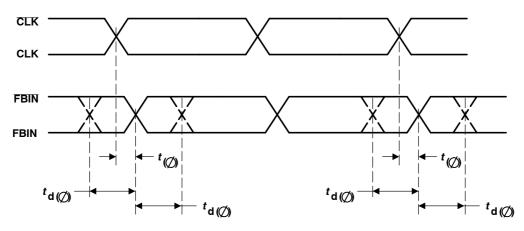
Figure 3. Cycle-to-Cycle Jitter



PARAMETER MEASUREMENT INFORMATION



(a) Static Phase Offset



(b) Dynamic Phase Offset

Figure 4. Static Phase Offset

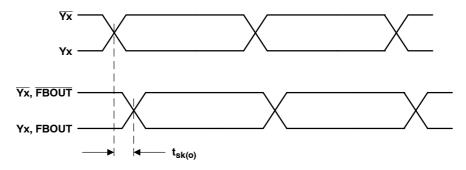


Figure 5. Output Skew

PARAMETER MEASUREMENT INFORMATION

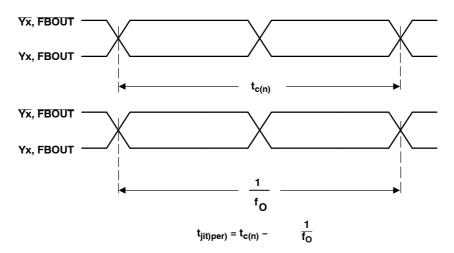


Figure 6. Period Jitter

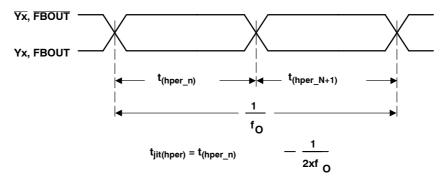


Figure 7. Half-Period Jitter

PARAMETER MEASUREMENT INFORMATION

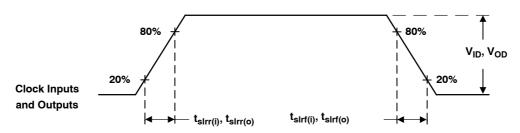


Figure 8. Input and Output Slew Rates

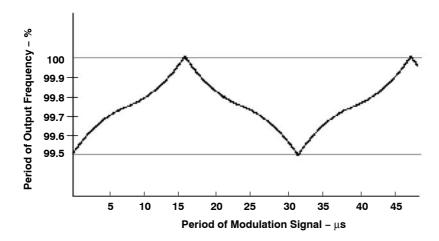
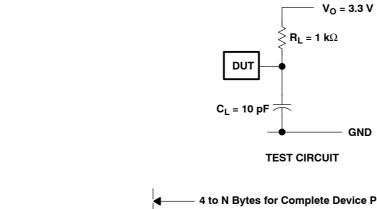
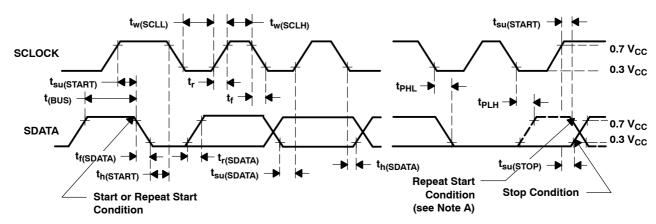


Figure 9. SSC Modulation Profile









VOLTAGE WAVEFORMS

BYTE	DESCRIPTION
1	Slave Address
2	Common (Dummy Value, Ignored)
3	Byte Count = N
4	Data Byte 0
5 – N	Data Byte 1 – N

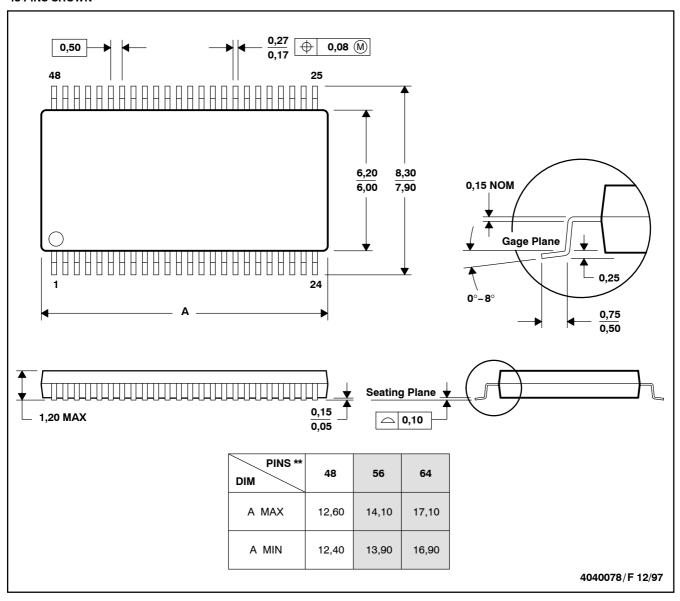
NOTE A: The repeat start condition is supported. If PWRDWN# is asserted SDATA will be set to off-state, high impedance.

Figure 10. Propagation Delay Times, t_r and t_f



MECHANICAL DATA

48 PINS SHOWN



NOTES: B. All linear dimensions are in millimeters.

C. This drawing is subject to change without notice.

D. Body dimensions do not include mold protrusion not to exceed 0,15.

E. Falls within JEDEC MO-153







8-May-2019

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing		Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CDCV850DGG	NRND	TSSOP	DGG	48	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CDCV850	
CDCV850DGGG4	NRND	TSSOP	DGG	48	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CDCV850	
CDCV850DGGR	NRND	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CDCV850	
CDCV850DGGRG4	NRND	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CDCV850	
CDCV850IDGG	NRND	TSSOP	DGG	48	40	TBD	Call TI	Call TI	-40 to 85	CDCV850-I	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

8-May-2019

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDCV850DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1

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*All dimensions are nominal

ĺ	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
	CDCV850DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0	

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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